



August 7, 2026

NEWS RELEASE

Enhanced Production Capacity for VSP™ Electro-Deposited Copper Foil for High-Frequency Circuit Boards

– Investing a total of 7 billion yen through 2030 to double production capacity to 1,400 tons per month –

Mitsui Kinzoku Company, Limited (President: Seiji Ikenobu; “Mitsui Kinzoku”) announces that it will expand production capacity of its VSP™ copper foil for high-frequency circuit boards manufactured at its Taiwan Plant (Taiwan Copper Foil Co., Ltd.) and Malaysia Plant (Mitsui Copper Foil (Malaysia) Sdn Bhd). In addition to the expansion of production capacity to 1,200 tons per month by FY2028 announced in a news release dated November 11, 2025 (“VSP™ Electro-Deposited Copper Foil for High-Frequency Circuit Boards Production Capacity Enhanced”), Mitsui Kinzoku has decided on plans to make further investments totaling 7 billion yen to boost monthly production capacity by 200 tons, to 1,400 tons per month.

Mitsui Kinzoku’s VSP™ copper foil for high-frequency circuit boards has been used in servers, routers, switches and other high-performance communication infrastructure equipment, because it significantly reduces transmission loss in printed circuit boards at high frequency signal bands. Currently, Mitsui Kinzoku is shifting HVLP5-graded products to the mass production phase for applications relating to AI infrastructure, and these products are increasingly used by leading global technology companies. The demand for Mitsui Kinzoku’s VSP™ is rapidly growing, and it is expected that it will increase.

These steps will result in an increase of Mitsui Kinzoku’s total production capacity. Mitsui Kinzoku will continue its efforts to additionally increase production capacity to meet the continued growth of demand in the future.

Mitsui Kinzoku will contribute to the realization of a sustainable society by implementing its vision for 2030, “Building new businesses — and the future — with our material intelligence,” based on its purpose, “We promote the well-being of the world through a spirit of exploration and diverse technologies.”

■ VSP™ production capacity (for reference)

Unit: tons/month	FY2025	FY2026	FY2027	FY2028	FY2030
Taiwan Plant	600	720	760	860	960
Malaysia Plant	120	120	240	340	440
Total	720	840	1,000	1,200	1,400

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General-purpose copper foil



VSP™

Photo: A reflection of an apple mango in a copper foil surface

* VSP™ is characterized by its outstanding surface smoothness comparable to that of a mirror.



Taiwan Plant

(Taiwan Copper Foil Co., Ltd. (“TCF”))



Malaysia Plant

(Mitsui Copper Foil (Malaysia) Sdn Bhd)

Photo: The Taiwan and Malaysia Plants, where the increase in production capacity is planned

(Reference)

Main functions of VSP™:

It is a copper foil for high-frequency circuit boards for communication infrastructure devices, including servers, switches, routers and base stations.